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For: ADHESIVE FILM REMOVAL METHOD AND APPARATUS

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contd

transferring the tension onto the substrate in the form of a compressive force, wherein the compressive force is applied to the substrate at a distance from the release line; and

advancing the release line and the compressive force towards the second end of the adhesive film, whereby the adhesive film is removed from the substrate.

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4.(AMENDED) A method according to claim 1, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

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5.(AMENDED) A method according to claim 1, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

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6.(AMENDED) A method according to claim 1, further comprising varying the distance between the compressive force and the release line.

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12.(AMENDED) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

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attaching the first end of the adhesive film to a winding device;
rotating the winding device to apply tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;
transferring the tension applied to the adhesive film onto the substrate in the form of a compressive force, with the compressive force being applied to the substrate by the winding device and wherein the compressive force is applied to the substrate at a distance from the release line; and

advancing the release line towards the second end of the adhesive film while winding the

adhesive film on the winding device, whereby the adhesive film is removed from the substrate.

17.(AMENDED) A method according to claim 12, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

18. (AMENDED) A method according to claim 12, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

19. (AMENDED) A method according to claim 12, further comprising varying the distance between the compressive force and the release line.

22.(AMENDED) An apparatus for removing adhesive film from a substrate, the apparatus comprising:

 a winding roll attached to a frame, the winding roll comprising a longitudinal axis;
 a motor operably connected to the winding roll for rotating the winding roll about its longitudinal axis; and
 a support roll rotatably attached to the frame, the support roll located a fixed distance from the winding roll, wherein the winding roll and the support roll are arranged on the frame such that tension applied to an adhesive film during removal of the adhesive film from the substrate is transferred to the substrate through the support roll, and wherein the support roll is not located at a release line of the adhesive film.